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(54) Title: APPARATUS FOR CLEANING SEMICONDUCTOR SUBSTRATES

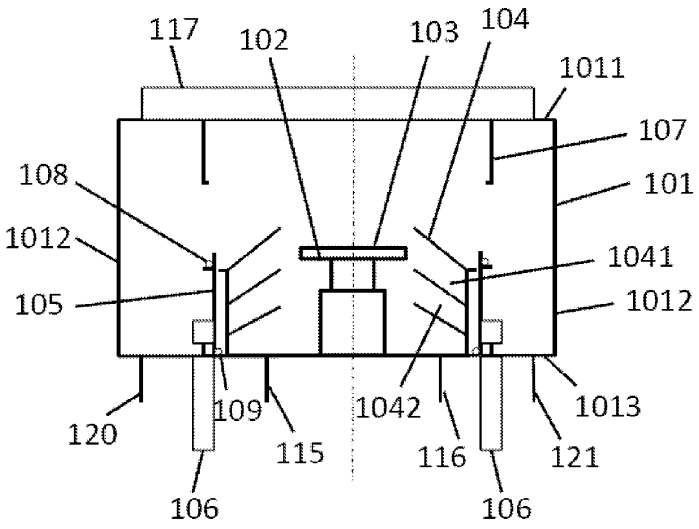


FIG 1A

(57) Abstract: An apparatus for cleaning semiconductor substrates includes a chamber (101), a chuck (102), a liquid collector (104), an enclosing wall (105), at least one driving mechanism (106), at least one internal dispenser (111), and at least one external dispenser (118). The chamber (101) has a top wall (1011), a side wall (1012) and a bottom wall (1013). The chuck (102) is disposed in the chamber (101) for holding a semiconductor substrate (103). The liquid collector (104) surrounds the chuck (102). The enclosing wall (105) surrounds the liquid collector (104). The at least one driving mechanism (106) drives the enclosing wall (105) to move up and down, wherein when the at least one driving mechanism (106) drives the enclosing wall (105) to move up, a seal room (110) is formed by the liquid collector (104), the enclosing wall (105), the top wall (1011) of the chamber (101), and the bottom wall (1013) of the chamber (101). The at least one internal dispenser (111) is disposed inside the seal room (110). The at least one external dispenser

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(118) is disposed outside the seal room (110). The at least one external dispenser (118) gets in and out the seal room (110) after the enclosing wall (105) is driven to move down.